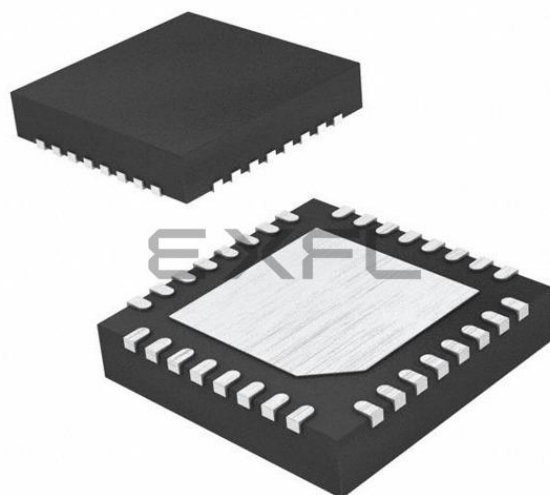




Welcome to [E-XFL.COM](https://www.e-xfl.com)

What is "[Embedded - Microcontrollers](#)"?

"[Embedded - Microcontrollers](#)" refer to small, integrated circuits designed to perform specific tasks within larger systems. These microcontrollers are essentially compact computers on a single chip, containing a processor core, memory, and programmable input/output peripherals. They are called "embedded" because they are embedded within electronic devices to control various functions, rather than serving as standalone computers. Microcontrollers are crucial in modern electronics, providing the intelligence and control needed for a wide range of applications.

Applications of "[Embedded - Microcontrollers](#)"

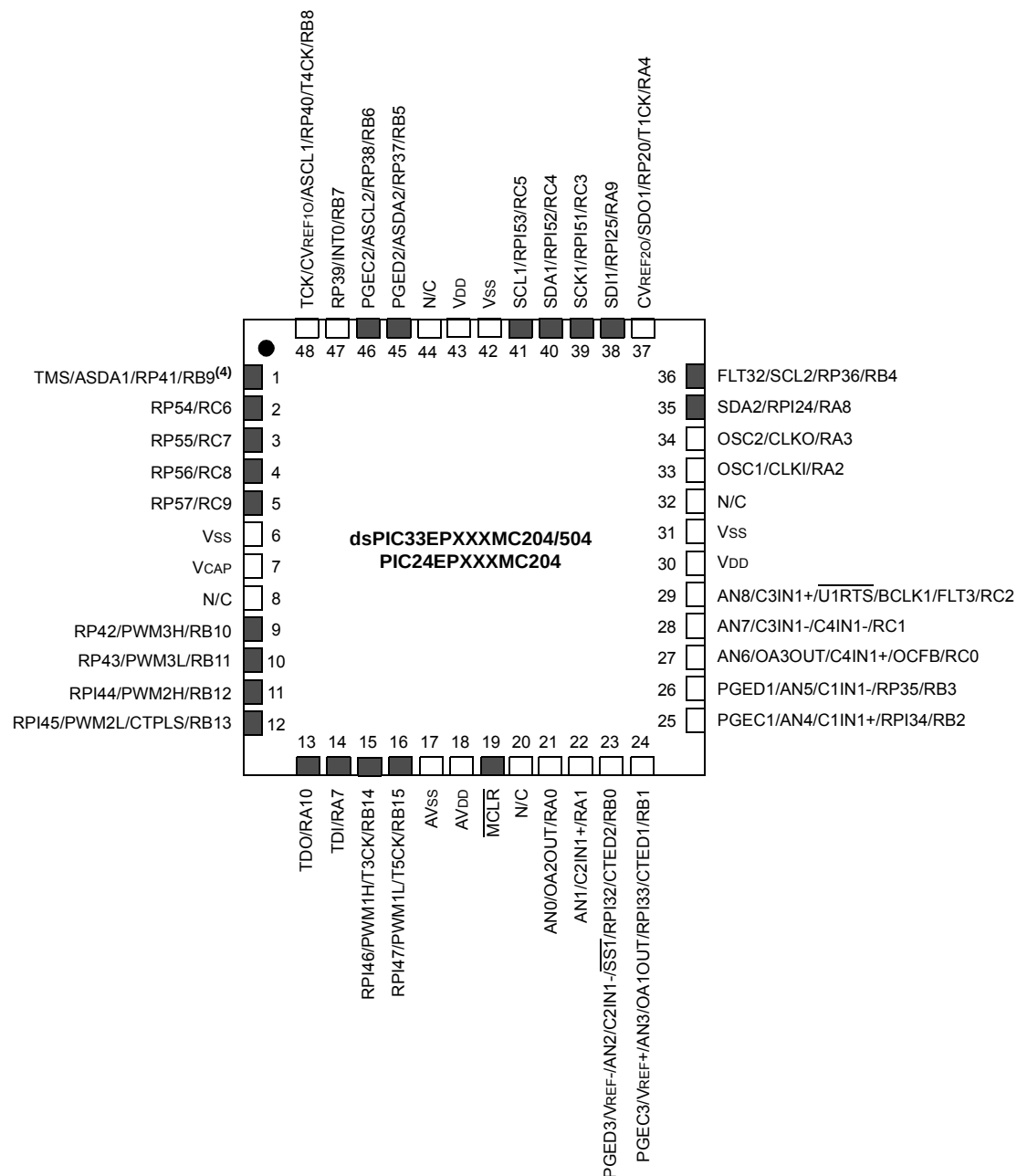
Details

Product Status	Obsolete
Core Processor	dsPIC
Core Size	16-Bit
Speed	60 MIPS
Connectivity	I ² C, IrDA, LINbus, QEI, SPI, UART/USART
Peripherals	Brown-out Detect/Reset, DMA, Motor Control PWM, POR, PWM, WDT
Number of I/O	21
Program Memory Size	32KB (10.7K x 24)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	2K x 16
Voltage - Supply (Vcc/Vdd)	3V ~ 3.6V
Data Converters	A/D 6x10b/12b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 125°C (TA)
Mounting Type	Surface Mount
Package / Case	28-VQFN Exposed Pad
Supplier Device Package	28-QFN-S (6x6)
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/dspic33ep32mc202t-e-mm

Pin Diagrams (Continued)



■ = Pins are up to 5V tolerant



- Note 1:** The RPN/RPIN pins can be used by any remappable peripheral with some limitation. See **Section 11.4 “Peripheral Pin Select (PPS)”** for available peripherals and for information on limitations.
- 2:** Every I/O port pin (RAX-RGX) can be used as a Change Notification pin (CNAX-CNGX). See **Section 11.0 “I/O Ports”** for more information.
- 3:** The metal pad at the bottom of the device is not connected to any pins and is recommended to be connected to VSS externally.
- 4:** There is an internal pull-up resistor connected to the TMS pin when the JTAG interface is active. See the JTAGEN bit field in Table 27-2.

Referenced Sources

This device data sheet is based on the following individual chapters of the “*dsPIC33/PIC24 Family Reference Manual*”. These documents should be considered as the general reference for the operation of a particular module or device feature.

Note 1: To access the documents listed below, browse to the documentation section of the dsPIC33EP64MC506 product page of the Microchip web site (www.microchip.com) or select a family reference manual section from the following list.

In addition to parameters, features and other documentation, the resulting page provides links to the related family reference manual sections.

- “**Introduction**” (DS70573)
- “**CPU**” (DS70359)
- “**Data Memory**” (DS70595)
- “**Program Memory**” (DS70613)
- “**Flash Programming**” (DS70609)
- “**Interrupts**” (DS70600)
- “**Oscillator**” (DS70580)
- “**Reset**” (DS70602)
- “**Watchdog Timer and Power-Saving Modes**” (DS70615)
- “**I/O Ports**” (DS70598)
- “**Timers**” (DS70362)
- “**Input Capture**” (DS70352)
- “**Output Compare**” (DS70358)
- “**High-Speed PWM**” (DS70645)
- “**Quadrature Encoder Interface (QEI)**” (DS70601)
- “**Analog-to-Digital Converter (ADC)**” (DS70621)
- “**UART**” (DS70582)
- “**Serial Peripheral Interface (SPI)**” (DS70569)
- “**Inter-Integrated Circuit (I²C™)**” (DS70330)
- “**Enhanced Controller Area Network (ECAN™)**” (DS70353)
- “**Direct Memory Access (DMA)**” (DS70348)
- “**CodeGuard™ Security**” (DS70634)
- “**Programming and Diagnostics**” (DS70608)
- “**Op Amp/Comparator**” (DS70357)
- “**Programmable Cyclic Redundancy Check (CRC)**” (DS70346)
- “**Device Configuration**” (DS70618)
- “**Peripheral Trigger Generator (PTG)**” (DS70669)
- “**Charge Time Measurement Unit (CTMU)**” (DS70661)

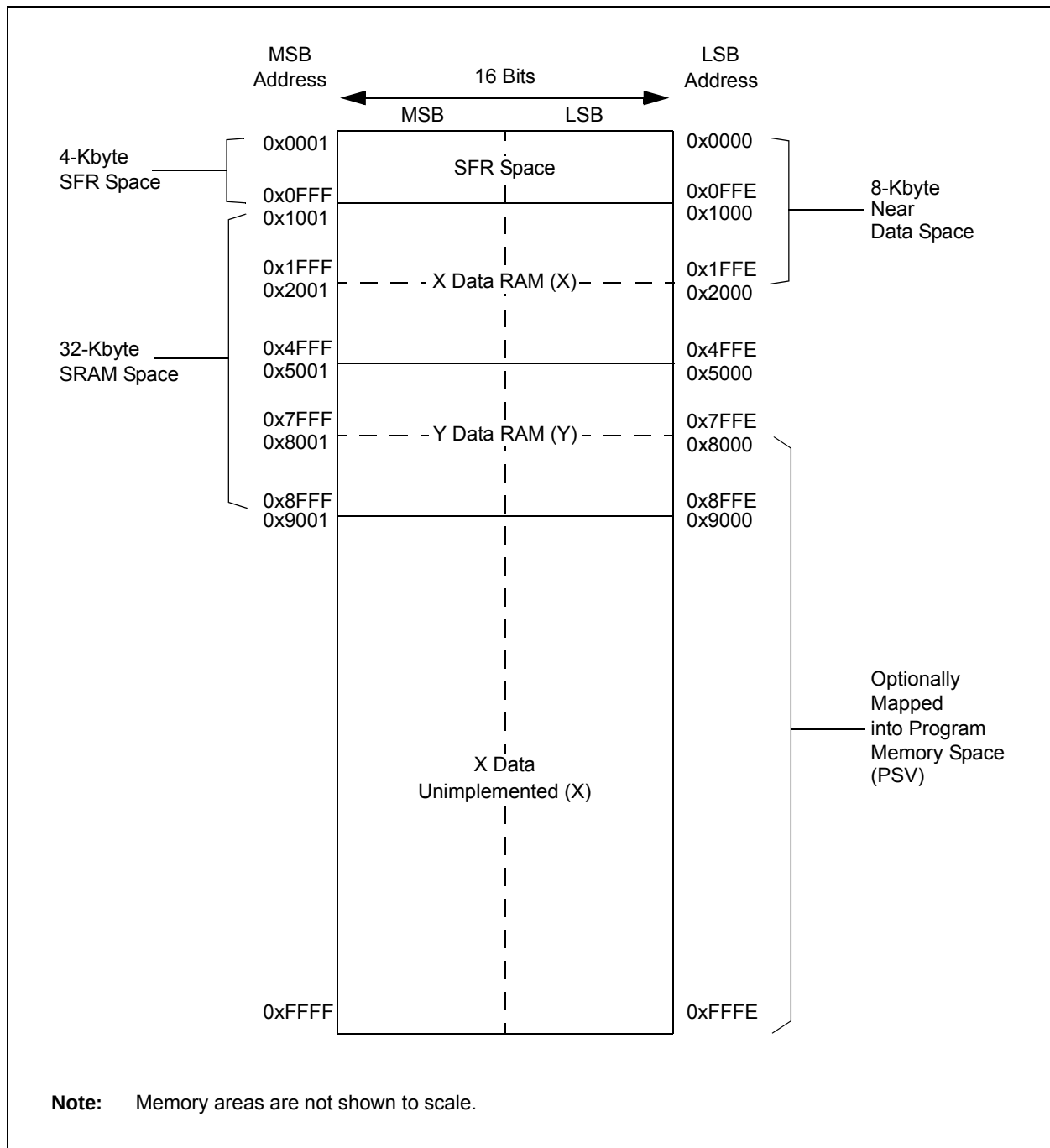
FIGURE 4-10: DATA MEMORY MAP FOR dsPIC33EP256MC20X/50X AND dsPIC33EP256GP50X DEVICES

TABLE 4-2: CPU CORE REGISTER MAP FOR PIC24EPXXXGP/MC20X DEVICES ONLY

File Name	Addr.	Bit 15	Bit 14	Bit 13	Bit 12	Bit 11	Bit 10	Bit 9	Bit 8	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	All Resets	
W0	0000	W0 (WREG)																XXXX	
W1	0002	W1																XXXX	
W2	0004	W2																XXXX	
W3	0006	W3																XXXX	
W4	0008	W4																XXXX	
W5	000A	W5																XXXX	
W6	000C	W6																XXXX	
W7	000E	W7																XXXX	
W8	0010	W8																XXXX	
W9	0012	W9																XXXX	
W10	0014	W10																XXXX	
W11	0016	W11																XXXX	
W12	0018	W12																XXXX	
W13	001A	W13																XXXX	
W14	001C	W14																XXXX	
W15	001E	W15																XXXX	
SPLIM	0020	SPLIM<15:0>																0000	
PCL	002E	PCL<15:1>																—	0000
PCH	0030	—	—	—	—	—	—	—	—	—	PCH<6:0>							0000	
DSRPAG	0032	—	—	—	—	—	—	DSRPAG<9:0>										0001	
DSWPAG	0034	—	—	—	—	—	—	—	DSWPAG<8:0>										0001
RCOUNT	0036	RCOUNT<15:0>																0000	
SR	0042	—	—	—	—	—	—	—	DC	IPL2	IPL1	IPL0	RA	N	OV	Z	C	0000	
CORCON	0044	VAR	—	—	—	—	—	—	—	—	—	—	—	IPL3	SFA	—	—	0020	
DISICNT	0052	—	—	DISICNT<13:0>														0000	
TBLPAG	0054	—	—	—	—	—	—	—	—	TBLPAG<7:0>									0000
MSTRPR	0058	MSTRPR<15:0>																0000	

Legend: x = unknown value on Reset, — = unimplemented, read as '0'. Reset values are shown in hexadecimal.

TABLE 4-49: PORTD REGISTER MAP FOR PIC24EPXXXGP/MC206 AND dsPIC33EPXXXGP/MC206/506 DEVICES ONLY

File Name	Addr.	Bit 15	Bit 14	Bit 13	Bit 12	Bit 11	Bit 10	Bit 9	Bit 8	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	All Resets
TRISD	0E30	—	—	—	—	—	—	—	TRISD8	—	TRISD6	TRISD5	—	—	—	—	—	0160
PORTD	0E32	—	—	—	—	—	—	—	RD8	—	RD6	RD5	—	—	—	—	—	xxxx
LATD	0E34	—	—	—	—	—	—	—	LATD8	—	LATD6	LATD5	—	—	—	—	—	xxxx
ODCD	0E36	—	—	—	—	—	—	—	ODCD8	—	ODCD6	ODCD5	—	—	—	—	—	0000
CNEND	0E38	—	—	—	—	—	—	—	CNIED8	—	CNIED6	CNIED5	—	—	—	—	—	0000
CNPUD	0E3A	—	—	—	—	—	—	—	CNPUD8	—	CNPUD6	CNPUD5	—	—	—	—	—	0000
CNPDD	0E3C	—	—	—	—	—	—	—	CNPDD8	—	CNPDD6	CNPDD5	—	—	—	—	—	0000

Legend: x = unknown value on Reset, — = unimplemented, read as '0'. Reset values are shown in hexadecimal.

TABLE 4-50: PORTE REGISTER MAP FOR PIC24EPXXXGP/MC206 AND dsPIC33EPXXXGP/MC206/506 DEVICES ONLY

File Name	Addr.	Bit 15	Bit 14	Bit 13	Bit 12	Bit 11	Bit 10	Bit 9	Bit 8	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	All Resets
TRISE	0E40	TRISE15	TRISE14	TRISE13	TRISE12	—	—	—	—	—	—	—	—	—	—	—	—	F000
PORTE	0E42	RE15	RE14	RE13	RE12	—	—	—	—	—	—	—	—	—	—	—	—	xxxx
LATE	0E44	LATE15	LATE14	LATE13	LATE12	—	—	—	—	—	—	—	—	—	—	—	—	xxxx
ODCE	0E46	ODCE15	ODCE14	ODCE13	ODCE12	—	—	—	—	—	—	—	—	—	—	—	—	0000
CNENE	0E48	CNIEE15	CNIEE14	CNIEE13	CNIEE12	—	—	—	—	—	—	—	—	—	—	—	—	0000
CNPUE	0E4A	CNPUE15	CNPUE14	CNPUE13	CNPUE12	—	—	—	—	—	—	—	—	—	—	—	—	0000
CNPDE	0E4C	CNPDE15	CNPDE14	CNPDE13	CNPDE12	—	—	—	—	—	—	—	—	—	—	—	—	0000
ANSELE	0E4E	ANSE15	ANSE14	ANSE13	ANSE12	—	—	—	—	—	—	—	—	—	—	—	—	F000

Legend: x = unknown value on Reset, — = unimplemented, read as '0'. Reset values are shown in hexadecimal.

TABLE 4-51: PORTF REGISTER MAP FOR PIC24EPXXXGP/MC206 AND dsPIC33EPXXXGP/MC206/506 DEVICES ONLY

File Name	Addr.	Bit 15	Bit 14	Bit 13	Bit 12	Bit 11	Bit 10	Bit 9	Bit 8	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	All Resets
TRISF	0E50	—	—	—	—	—	—	—	—	—	—	—	—	—	—	TRISF1	TRISF0	0003
PORTF	0E52	—	—	—	—	—	—	—	—	—	—	—	—	—	—	RF1	RF0	xxxx
LATF	0E54	—	—	—	—	—	—	—	—	—	—	—	—	—	—	LATF1	LATF0	xxxx
ODCF	0E56	—	—	—	—	—	—	—	—	—	—	—	—	—	—	ODCF1	ODCF0	0000
CNENF	0E58	—	—	—	—	—	—	—	—	—	—	—	—	—	—	CNIEF1	CNIEF0	0000
CNPUF	0E5A	—	—	—	—	—	—	—	—	—	—	—	—	—	—	CNPUF1	CNPUF0	0000
CNPDF	0E5C	—	—	—	—	—	—	—	—	—	—	—	—	—	—	CNPDF1	CNPDF0	0000

Legend: x = unknown value on Reset, — = unimplemented, read as '0'. Reset values are shown in hexadecimal.

4.4.3 DATA MEMORY ARBITRATION AND BUS MASTER PRIORITY

EDS accesses from bus masters in the system are arbitrated.

The arbiter for data memory (including EDS) arbitrates between the CPU, the DMA and the ICD module. In the event of coincidental access to a bus by the bus masters, the arbiter determines which bus master access has the highest priority. The other bus masters are suspended and processed after the access of the bus by the bus master with the highest priority.

By default, the CPU is Bus Master 0 (M0) with the highest priority and the ICD is Bus Master 4 (M4) with the lowest priority. The remaining bus master (DMA Controller) is allocated to M3 (M1 and M2 are reserved and cannot be used). The user application may raise or lower the priority of the DMA Controller to be above that of the CPU by setting the appropriate bits in the EDS Bus Master Priority Control (MSTRPR) register. All bus masters with raised priorities will maintain the same priority relationship relative to each other (i.e., M1 being highest and M3 being lowest, with M2 in between). Also, all the bus masters with priorities below

that of the CPU maintain the same priority relationship relative to each other. The priority schemes for bus masters with different MSTRPR values are tabulated in Table 4-62.

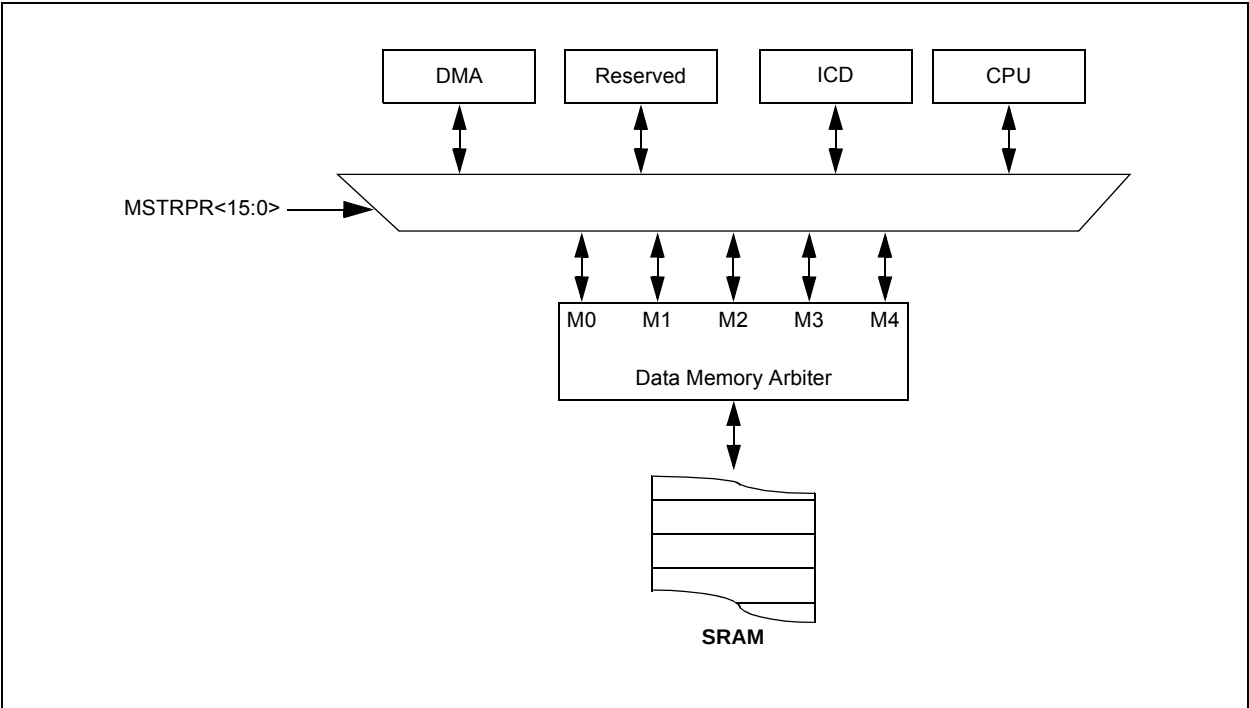
This bus master priority control allows the user application to manipulate the real-time response of the system, either statically during initialization or dynamically in response to real-time events.

TABLE 4-62: DATA MEMORY BUS ARBITER PRIORITY

Priority	MSTRPR<15:0> Bit Setting ⁽¹⁾	
	0x0000	0x0020
M0 (highest)	CPU	DMA
M1	Reserved	CPU
M2	Reserved	Reserved
M3	DMA	Reserved
M4 (lowest)	ICD	ICD

Note 1: All other values of MSTRPR<15:0> are reserved.

FIGURE 4-18: ARBITER ARCHITECTURE



4.5.3 MOVE AND ACCUMULATOR INSTRUCTIONS

Move instructions, which apply to dsPIC33EPXXXGP50X, dsPIC33EPXXXMC20X/50X and PIC24EPXXXGP/MC20X devices, and the DSP accumulator class of instructions, which apply to the dsPIC33EPXXXMC20X/50X and dsPIC33EPXXXGP50X devices, provide a greater degree of addressing flexibility than other instructions. In addition to the addressing modes supported by most MCU instructions, move and accumulator instructions also support Register Indirect with Register Offset Addressing mode, also referred to as Register Indexed mode.

Note: For the MOV instructions, the addressing mode specified in the instruction can differ for the source and destination EA. However, the 4-bit Wb (Register Offset) field is shared by both source and destination (but typically only used by one).

In summary, the following addressing modes are supported by move and accumulator instructions:

- Register Direct
- Register Indirect
- Register Indirect Post-modified
- Register Indirect Pre-modified
- Register Indirect with Register Offset (Indexed)
- Register Indirect with Literal Offset
- 8-Bit Literal
- 16-Bit Literal

Note: Not all instructions support all the addressing modes given above. Individual instructions may support different subsets of these addressing modes.

4.5.4 MAC INSTRUCTIONS (dsPIC33EPXXXMC20X/50X and dsPIC33EPXXXGP50X DEVICES ONLY)

The dual source operand DSP instructions (CLR, ED, EDAC, MAC, MPY, MPY.N, MOVSA and MSC), also referred to as MAC instructions, use a simplified set of addressing modes to allow the user application to effectively manipulate the Data Pointers through register indirect tables.

The Two-Source Operand Prefetch registers must be members of the set: {W8, W9, W10, W11}. For data reads, W8 and W9 are always directed to the X RAGU, and W10 and W11 are always directed to the Y AGU. The Effective Addresses generated (before and after modification) must therefore, be valid addresses within X Data Space for W8 and W9, and Y Data Space for W10 and W11.

Note: Register Indirect with Register Offset Addressing mode is available only for W9 (in X space) and W11 (in Y space).

In summary, the following addressing modes are supported by the MAC class of instructions:

- Register Indirect
- Register Indirect Post-Modified by 2
- Register Indirect Post-Modified by 4
- Register Indirect Post-Modified by 6
- Register Indirect with Register Offset (Indexed)

4.5.5 OTHER INSTRUCTIONS

Besides the addressing modes outlined previously, some instructions use literal constants of various sizes. For example, BRA (branch) instructions use 16-bit signed literals to specify the branch destination directly, whereas the DISI instruction uses a 14-bit unsigned literal field. In some instructions, such as ULNK, the source of an operand or result is implied by the opcode itself. Certain operations, such as a NOP, do not have any operands.

REGISTER 8-9: DSADRH: DMA MOST RECENT RAM HIGH ADDRESS REGISTER

U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
—	—	—	—	—	—	—	—
bit 15				bit 8			

R-0	R-0	R-0	R-0	R-0	R-0	R-0	R-0
DSADR<23:16>							
bit 7				bit 0			

Legend:

R = Readable bit

W = Writable bit

U = Unimplemented bit, read as '0'

-n = Value at POR

'1' = Bit is set

'0' = Bit is cleared

x = Bit is unknown

bit 15-8 **Unimplemented:** Read as '0'bit 7-0 **DSADR<23:16>:** Most Recent DMA Address Accessed by DMA bits**REGISTER 8-10: DSADRL: DMA MOST RECENT RAM LOW ADDRESS REGISTER**

R-0	R-0	R-0	R-0	R-0	R-0	R-0	R-0
DSADR<15:8>							
bit 15				bit 8			

R-0	R-0	R-0	R-0	R-0	R-0	R-0	R-0
DSADR<7:0>							
bit 7				bit 0			

Legend:

R = Readable bit

W = Writable bit

U = Unimplemented bit, read as '0'

-n = Value at POR

'1' = Bit is set

'0' = Bit is cleared

x = Bit is unknown

bit 15-0 **DSADR<15:0>:** Most Recent DMA Address Accessed by DMA bits

NOTES:

9.0 OSCILLATOR CONFIGURATION

Note 1: This data sheet summarizes the features of the dsPIC33EPXXXGP50X, dsPIC33EPXXXMC20X/50X and PIC24EPXXXGP/MC20X families of devices. It is not intended to be a comprehensive reference source. To complement the information in this data sheet, refer to “**Oscillator**” (DS70580) in the “*dsPIC33/PIC24 Family Reference Manual*”, which is available from the Microchip web site (www.microchip.com).

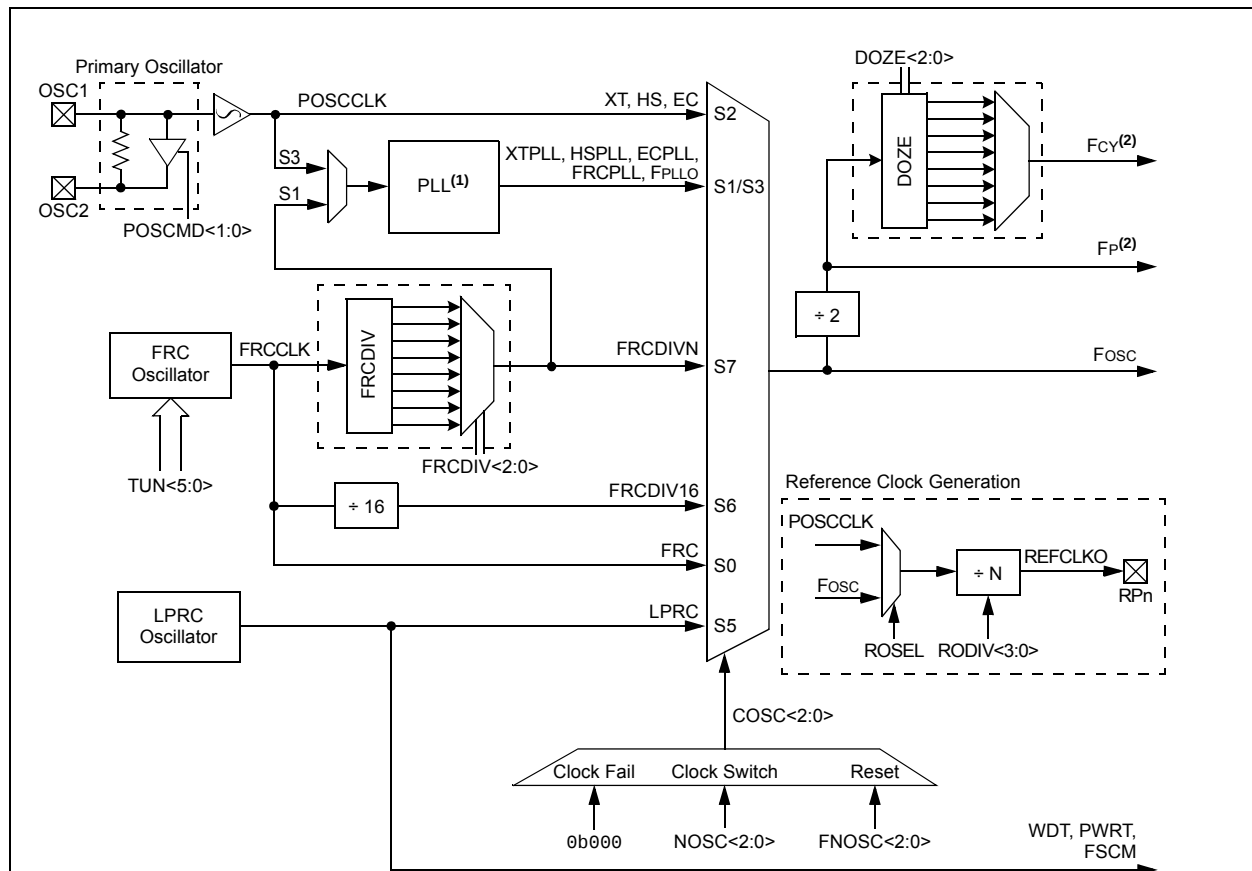
2: Some registers and associated bits described in this section may not be available on all devices. Refer to **Section 4.0 “Memory Organization”** in this data sheet for device-specific register and bit information.

The dsPIC33EPXXXGP50X, dsPIC33EPXXXMC20X/50X and PIC24EPXXXGP/MC20X oscillator system provides:

- On-chip Phase-Locked Loop (PLL) to boost internal operating frequency on select internal and external oscillator sources
- On-the-fly clock switching between various clock sources
- Doze mode for system power savings
- Fail-Safe Clock Monitor (FSCM) that detects clock failure and permits safe application recovery or shutdown
- Configuration bits for clock source selection

A simplified diagram of the oscillator system is shown in Figure 9-1.

FIGURE 9-1: OSCILLATOR SYSTEM DIAGRAM



Note 1: See Figure 9-2 for PLL details.

2: The term, Fp, refers to the clock source for all peripherals, while Fcy refers to the clock source for the CPU. Throughout this document, Fcy and Fp are used interchangeably, except in the case of Doze mode. Fp and Fcy will be different when Doze mode is used with a doze ratio of 1:2 or lower.

10.0 POWER-SAVING FEATURES

Note 1: This data sheet summarizes the features of the dsPIC33EPXXXGP50X, dsPIC33EPXXXMC20X/50X and PIC24EPXXXGP/MC20X families of devices. It is not intended to be a comprehensive reference source. To complement the information in this data sheet, refer to **“Watchdog Timer and Power-Saving Modes”** (DS70615) in the *“dsPIC33/PIC24 Family Reference Manual”*, which is available from the Microchip web site (www.microchip.com).

2: Some registers and associated bits described in this section may not be available on all devices. Refer to **Section 4.0 “Memory Organization”** in this data sheet for device-specific register and bit information.

The dsPIC33EPXXXGP50X, dsPIC33EPXXXMC20X/50X and PIC24EPXXXGP/MC20X devices provide the ability to manage power consumption by selectively managing clocking to the CPU and the peripherals. In general, a lower clock frequency and a reduction in the number of peripherals being clocked constitutes lower consumed power.

dsPIC33EPXXXGP50X, dsPIC33EPXXXMC20X/50X and PIC24EPXXXGP/MC20X devices can manage power consumption in four ways:

- Clock Frequency
- Instruction-Based Sleep and Idle modes
- Software-Controlled Doze mode
- Selective Peripheral Control in Software

Combinations of these methods can be used to selectively tailor an application's power consumption while still maintaining critical application features, such as timing-sensitive communications.

10.1 Clock Frequency and Clock Switching

The dsPIC33EPXXXGP50X, dsPIC33EPXXXMC20X/50X and PIC24EPXXXGP/MC20X devices allow a wide range of clock frequencies to be selected under application control. If the system clock configuration is not locked, users can choose low-power or high-precision oscillators by simply changing the NOSCx bits (OSCCON<10:8>). The process of changing a system clock during operation, as well as limitations to the process, are discussed in more detail in **Section 9.0 “Oscillator Configuration”**.

10.2 Instruction-Based Power-Saving Modes

The dsPIC33EPXXXGP50X, dsPIC33EPXXXMC20X/50X and PIC24EPXXXGP/MC20X devices have two special power-saving modes that are entered through the execution of a special PWRSAV instruction. Sleep mode stops clock operation and halts all code execution. Idle mode halts the CPU and code execution, but allows peripheral modules to continue operation. The assembler syntax of the PWRSAV instruction is shown in Example 10-1.

Note: SLEEP_MODE and IDLE_MODE are constants defined in the assembler include file for the selected device.

Sleep and Idle modes can be exited as a result of an enabled interrupt, WDT time-out or a device Reset. When the device exits these modes, it is said to “wake-up”.

EXAMPLE 10-1: PWRSAV INSTRUCTION SYNTAX

```
PWRSAV #SLEEP_MODE    ; Put the device into Sleep mode
PWRSAV #IDLE_MODE     ; Put the device into Idle mode
```

18.1 SPI Helpful Tips

1. In Frame mode, if there is a possibility that the master may not be initialized before the slave:
 - a) If FRMPOL (SPIxCON2<13>) = 1, use a pull-down resistor on $\overline{SSx}$.
 - b) If FRMPOL = 0, use a pull-up resistor on $\overline{SSx}$.

Note: This insures that the first frame transmission after initialization is not shifted or corrupted.

2. In Non-Framed 3-Wire mode, (i.e., not using $\overline{SSx}$ from a master):
 - a) If CKP (SPIxCON1<6>) = 1, always place a pull-up resistor on $\overline{SSx}$.
 - b) If CKP = 0, always place a pull-down resistor on $\overline{SSx}$.

Note: This will insure that during power-up and initialization the master/slave will not lose Sync due to an errant SCKx transition that would cause the slave to accumulate data shift errors for both transmit and receive appearing as corrupted data.

3. FRMEN (SPIxCON2<15>) = 1 and SSEN (SPIxCON1<7>) = 1 are exclusive and invalid. In Frame mode, SCKx is continuous and the Frame Sync pulse is active on the $\overline{SSx}$ pin, which indicates the start of a data frame.

Note: Not all third-party devices support Frame mode timing. Refer to the SPIx specifications in **Section 30.0 "Electrical Characteristics"** for details.

4. In Master mode only, set the SMP bit (SPIxCON1<9>) to a '1' for the fastest SPIx data rate possible. The SMP bit can only be set at the same time or after the MSTEN bit (SPIxCON1<5>) is set.

To avoid invalid slave read data to the master, the user's master software must ensure enough time for slave software to fill its write buffer before the user application initiates a master write/read cycle. It is always advisable to preload the SPIxBUF Transmit register in advance of the next master transaction cycle. SPIxBUF is transferred to the SPIx Shift register and is empty once the data transmission begins.

18.2 SPI Resources

Many useful resources are provided on the main product page of the Microchip web site for the devices listed in this data sheet. This product page, which can be accessed using this link, contains the latest updates and additional information.

Note: In the event you are not able to access the product page using the link above, enter this URL in your browser:
<http://www.microchip.com/wwwproducts/Devices.aspx?dDocName=en555464>

18.2.1 KEY RESOURCES

- **"Serial Peripheral Interface (SPI)"** (DS70569) in the *"dsPIC33/PIC24 Family Reference Manual"*
- Code Samples
- Application Notes
- Software Libraries
- Webinars
- All Related *"dsPIC33/PIC24 Family Reference Manual"* Sections
- Development Tools

FIGURE 30-2: EXTERNAL CLOCK TIMING

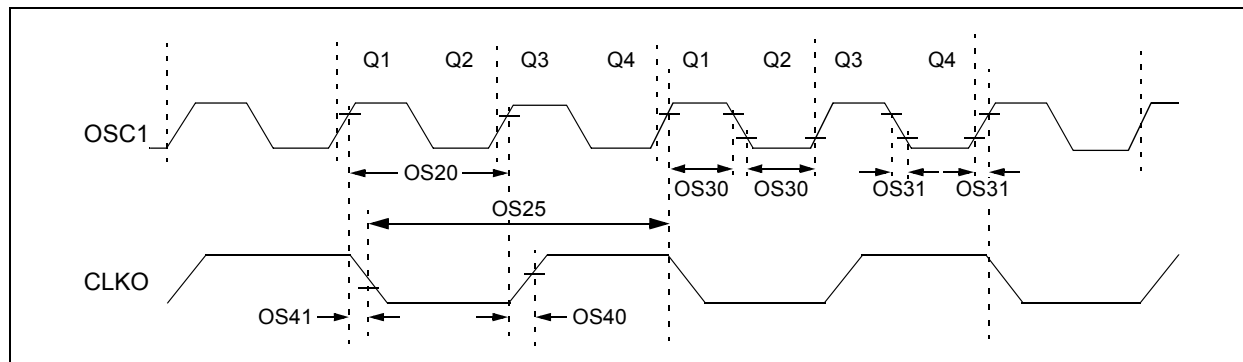


TABLE 30-17: EXTERNAL CLOCK TIMING REQUIREMENTS

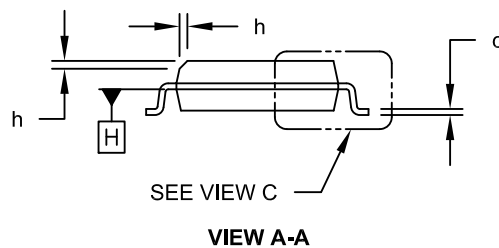
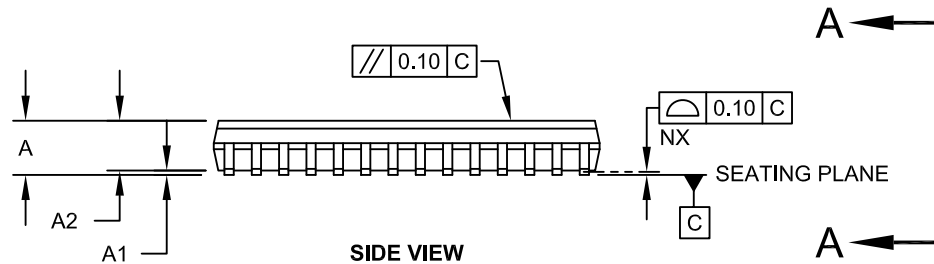
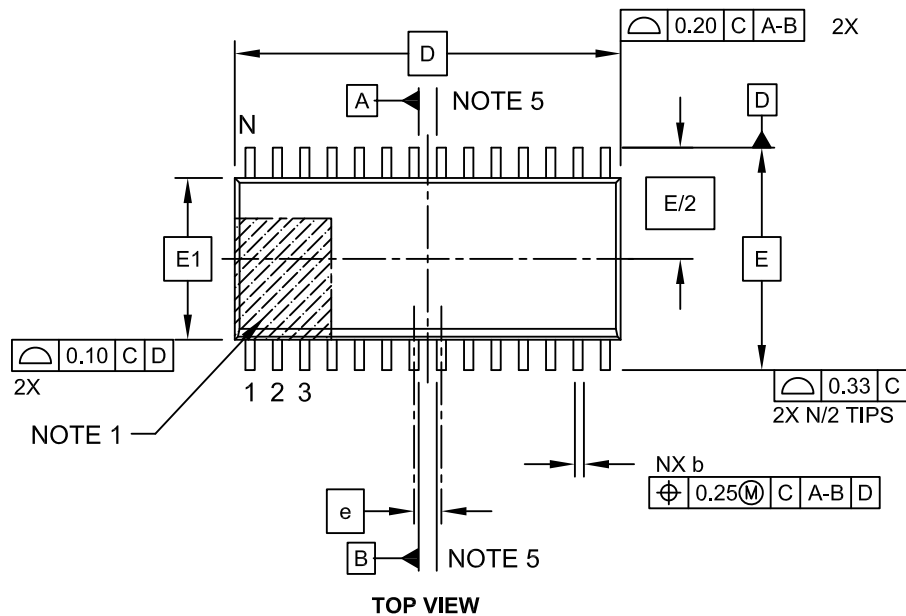
AC CHARACTERISTICS			Standard Operating Conditions: 3.0V to 3.6V (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +125°C for Extended				
Param No.	Symb	Characteristic	Min.	Typ. ⁽¹⁾	Max.	Units	Conditions
OS10	FIN	External CLKI Frequency (External clocks allowed only in EC and ECPLL modes)	DC	—	60	MHz	EC
		Oscillator Crystal Frequency	3.5 10	— —	10 25	MHz MHz	XT HS
OS20	Tosc	Tosc = 1/Fosc	8.33	—	DC	ns	+125°C
		Tosc = 1/Fosc	7.14	—	DC	ns	+85°C
OS25	Tcy	Instruction Cycle Time ⁽²⁾	16.67	—	DC	ns	+125°C
		Instruction Cycle Time ⁽²⁾	14.28	—	DC	ns	+85°C
OS30	TosL, TosH	External Clock in (OSC1) High or Low Time	0.45 x Tosc	—	0.55 x Tosc	ns	EC
OS31	TosR, TosF	External Clock in (OSC1) Rise or Fall Time	—	—	20	ns	EC
OS40	TckR	CLKO Rise Time ^(3,4)	—	5.2	—	ns	
OS41	TckF	CLKO Fall Time ^(3,4)	—	5.2	—	ns	
OS42	GM	External Oscillator Transconductance ⁽⁴⁾	—	12	—	mA/V	HS, VDD = 3.3V, TA = +25°C
			—	6	—	mA/V	XT, VDD = 3.3V, TA = +25°C

Note 1: Data in "Typical" column is at 3.3V, +25°C unless otherwise stated.

- 2:** Instruction cycle period (Tcy) equals two times the input oscillator time base period. All specified values are based on characterization data for that particular oscillator type under standard operating conditions with the device executing code. Exceeding these specified limits may result in an unstable oscillator operation and/or higher than expected current consumption. All devices are tested to operate at "Minimum" values with an external clock applied to the OSC1 pin. When an external clock input is used, the "Maximum" cycle time limit is "DC" (no clock) for all devices.
- 3:** Measurements are taken in EC mode. The CLKO signal is measured on the OSC2 pin.
- 4:** This parameter is characterized, but not tested in manufacturing.

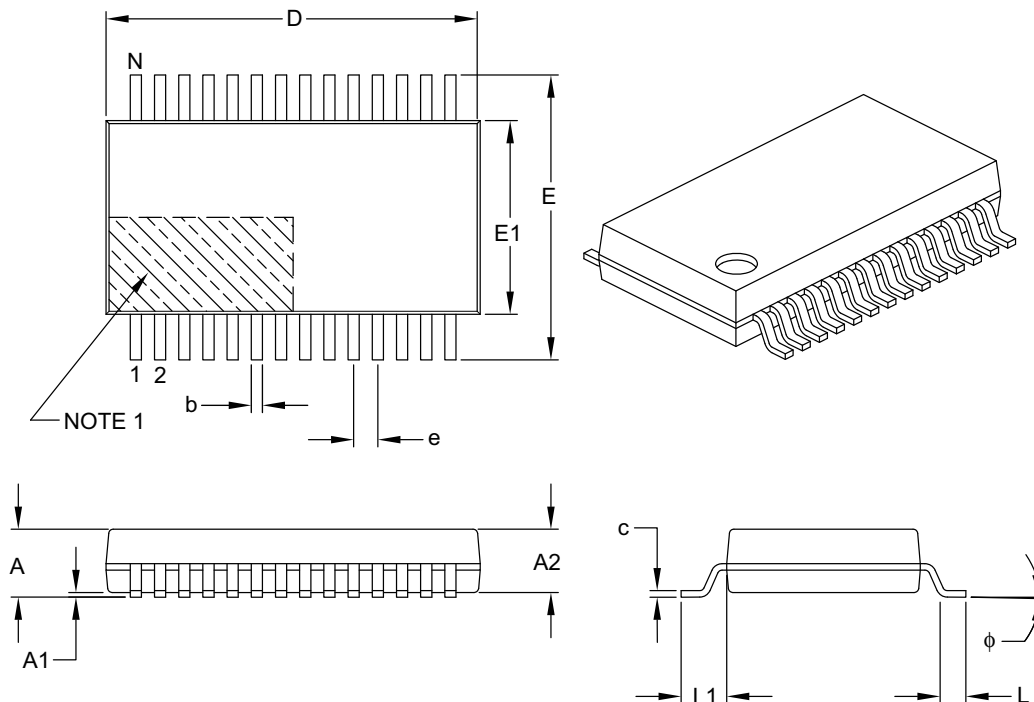
NOTES:

Note: For the most current package drawings, please see the Microchip Packaging Specification located at <http://www.microchip.com/packaging>



28-Lead Plastic Shrink Small Outline (SS) – 5.30 mm Body [SSOP]

Note: For the most current package drawings, please see the Microchip Packaging Specification located at <http://www.microchip.com/packaging>



Dimension Limits	Units	MILLIMETERS		
		MIN	NOM	MAX
Number of Pins	N	28		
Pitch	e	0.65 BSC		
Overall Height	A	–	–	2.00
Molded Package Thickness	A2	1.65	1.75	1.85
Standoff	A1	0.05	–	–
Overall Width	E	7.40	7.80	8.20
Molded Package Width	E1	5.00	5.30	5.60
Overall Length	D	9.90	10.20	10.50
Foot Length	L	0.55	0.75	0.95
Footprint	L1	1.25 REF		
Lead Thickness	c	0.09	–	0.25
Foot Angle	φ	0°	4°	8°
Lead Width	b	0.22	–	0.38

Notes:

- Pin 1 visual index feature may vary, but must be located within the hatched area.
- Dimensions D and E1 do not include mold flash or protrusions. Mold flash or protrusions shall not exceed 0.20 mm per side.
- Dimensioning and tolerancing per ASME Y14.5M.

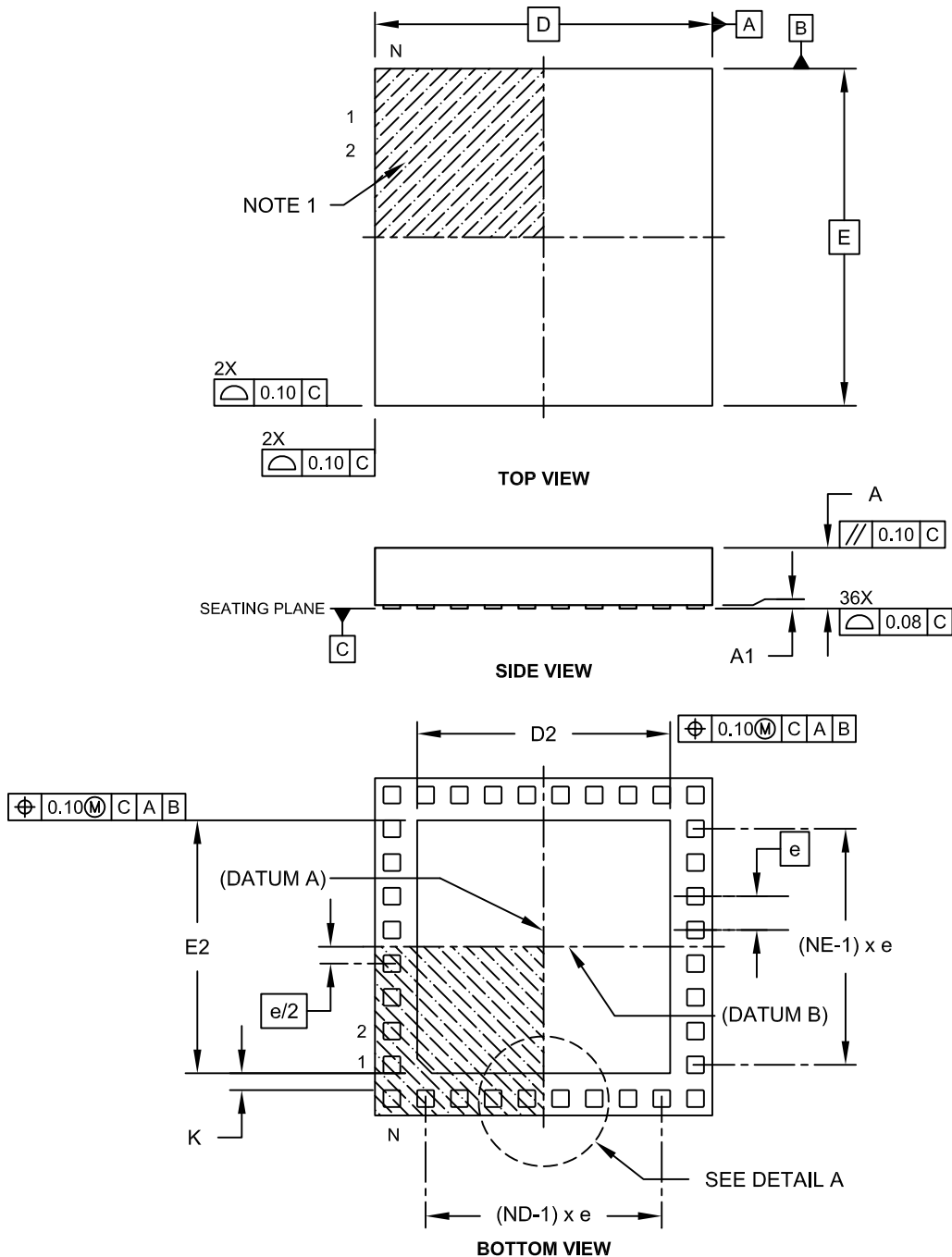
BSC: Basic Dimension. Theoretically exact value shown without tolerances.

REF: Reference Dimension, usually without tolerance, for information purposes only.

Microchip Technology Drawing C04-073B

36-Terminal Very Thin Thermal Leadless Array Package (TL) – 5x5x0.9 mm Body with Exposed Pad [VTLA]

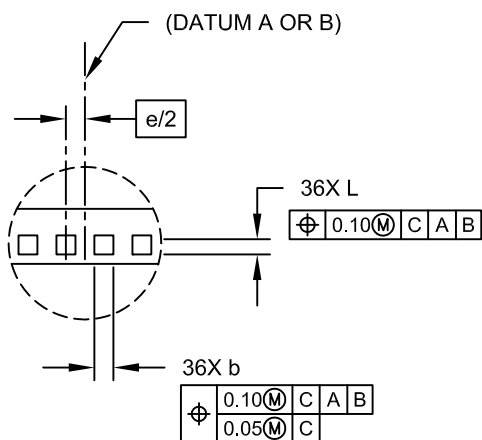
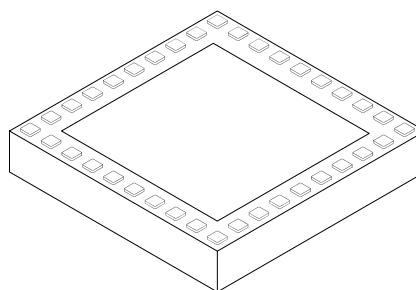
Note: For the most current package drawings, please see the Microchip Packaging Specification located at <http://www.microchip.com/packaging>



Microchip Technology Drawing C04-187C Sheet 1 of 2

36-Terminal Very Thin Thermal Leadless Array Package (TL) – 5x5x0.9 mm Body with Exposed Pad [VTLA]

Note: For the most current package drawings, please see the Microchip Packaging Specification located at <http://www.microchip.com/packaging>

**DETAIL A**

Dimension	Units	MILLIMETERS		
	Limits	MIN	NOM	MAX
Number of Pins	N	36		
Number of Pins per Side	ND	10		
Number of Pins per Side	NE	8		
Pitch	e	0.50 BSC		
Overall Height	A	0.80	0.90	1.00
Standoff	A1	0.025	-	0.075
Overall Width	E	5.00 BSC		
Exposed Pad Width	E2	3.60	3.75	3.90
Overall Length	D	5.00 BSC		
Exposed Pad Length	D2	3.60	3.75	3.90
Contact Width	b	0.20	0.25	0.30
Contact Length	L	0.20	0.25	0.30
Contact-to-Exposed Pad	K	0.20	-	-

Notes:

- Pin 1 visual index feature may vary, but must be located within the hatched area.
- Package is saw singulated.
- Dimensioning and tolerancing per ASME Y14.5M.
BSC: Basic Dimension. Theoretically exact value shown without tolerances.
REF: Reference Dimension, usually without tolerance, for information purposes only.

Microchip Technology Drawing C04-187C Sheet 2 of 2

INDEX

A

Absolute Maximum Ratings	401
AC Characteristics	413, 471
10-Bit ADC Conversion Requirements	465
12-Bit ADC Conversion Requirements	463
ADC Module	459
ADC Module (10-Bit Mode)	461, 473
ADC Module (12-Bit Mode)	460, 473
Capacitive Loading Requirements on Output Pins	413
DMA Module Requirements	465
ECANx I/O Requirements	454
External Clock	414
High-Speed PWMx Requirements	422
I/O Timing Requirements	416
I2Cx Bus Data Requirements (Master Mode)	451
I2Cx Bus Data Requirements (Slave Mode)	453
Input Capture x Requirements	420
Internal FRC Accuracy	415
Internal LPRC Accuracy	415
Internal RC Accuracy	472
Load Conditions	413, 471
OCx/PWMx Mode Requirements	421
Op Amp/Comparator Voltage Reference Settling Time Specifications	457
Output Compare x Requirements	421
PLL Clock	415, 471
QE1 External Clock Requirements	423
QE1 Index Pulse Requirements	425
Quadrature Decoder Requirements	424
Reset, Watchdog Timer, Oscillator Start-up Timer, Power-up Timer Requirements	417
SPI1 Master Mode (Full-Duplex, CKE = 0, CKP = x, SMP = 1) Requirements	441
SPI1 Master Mode (Full-Duplex, CKE = 1, CKP = x, SMP = 1) Requirements	440
SPI1 Master Mode (Half-Duplex, Transmit Only) Requirements	439
SPI1 Maximum Data/Clock Rate Summary	438
SPI1 Slave Mode (Full-Duplex, CKE = 0, CKP = 0, SMP = 0) Requirements	449
SPI1 Slave Mode (Full-Duplex, CKE = 0, CKP = 1, SMP = 0) Requirements	447
SPI1 Slave Mode (Full-Duplex, CKE = 1, CKP = 0, SMP = 0) Requirements	443
SPI1 Slave Mode (Full-Duplex, CKE = 1, CKP = 1, SMP = 0) Requirements	445
SPI2 Master Mode (Full-Duplex, CKE = 0, CKP = x, SMP = 1) Requirements	429
SPI2 Master Mode (Full-Duplex, CKE = 1, CKP = x, SMP = 1) Requirements	428
SPI2 Master Mode (Half-Duplex, Transmit Only) Requirements	427
SPI2 Maximum Data/Clock Rate Summary	426
SPI2 Slave Mode (Full-Duplex, CKE = 0, CKP = 0, SMP = 0) Requirements	437
SPI2 Slave Mode (Full-Duplex, CKE = 0, CKP = 1, SMP = 0) Requirements	435
SPI2 Slave Mode (Full-Duplex, CKE = 1, CKP = 0, SMP = 0) Requirements	431
SPI2 Slave Mode (Full-Duplex, CKE = 1, CKP = 1, SMP = 0) Requirements	433

Timer1 External Clock Requirements	418
Timer2/Timer4 External Clock Requirements	419
Timer3/Timer5 External Clock Requirements	419
UARTx I/O Requirements	454
ADC	
Control Registers	325
Helpful Tips	324
Key Features	321
Resources	324
Arithmetic Logic Unit (ALU)	44
Assembler	
MPASM Assembler	398
B	
Bit-Reversed Addressing	115
Example	116
Implementation	115
Sequence Table (16-Entry)	116
Block Diagrams	
Data Access from Program Space Address Generation	117
16-Bit Timer1 Module	203
ADC Conversion Clock Period	323
ADC with Connection Options for ANx Pins and Op Amps	322
Arbiter Architecture	110
BEMF Voltage Measurement Using ADC	34
Boost Converter Implementation	32
CALL Stack Frame	111
Comparator (Module 4)	356
Connections for On-Chip Voltage Regulator	384
CPU Core	36
CRC Module	373
CRC Shift Engine	374
CTMU Module	316
Digital Filter Interconnect	357
DMA Controller	141
DMA Controller Module	139
dsPIC33EPXXXGP50X, dsPIC33EPXXXMC20X/50X and PIC24EPXXXGP/MC20X	25
ECAN Module	288
EDS Read Address Generation	105
EDS Write Address Generation	106
Example of MCLR Pin Connections	30
High-Speed PWMx Architectural Overview	227
High-Speed PWMx Register Interconnection	228
I2Cx Module	274
Input Capture x	213
Interleaved PFC	34
Multiphase Synchronous Buck Converter	33
Multiplexing Remappable Output for RPN	180
Op Amp Configuration A	358
Op Amp Configuration B	359
Op Amp/Comparator Voltage Reference Module	356
Op Amp/Comparator x (Modules 1, 2, 3)	355
Oscillator System	153
Output Compare x Module	219
PLL	154
Programmer's Model	38
PTG Module	338
Quadrature Encoder Interface	250
Recommended Minimum Connection	30

TyCON (Timer3 and Timer5 Control).....	211	Input Capture x (ICx)	420
UxMODE (UARTx Mode).....	283	OCx/PWMx.....	421
UxSTA (UARTx Status and Control).....	285	Output Compare x (OCx).....	421
VEL1CNT (Velocity Counter 1).....	259	QEA/QEB Input	424
Resets	123	QE1 Module Index Pulse	425
Brown-out Reset (BOR).....	123	SPI1 Master Mode (Full-Duplex, CKE = 0, CKP = x, SMP = 1)	441
Configuration Mismatch Reset (CM).....	123	SPI1 Master Mode (Full-Duplex, CKE = 1, CKP = x, SMP = 1)	440
Illegal Condition Reset (IOPUWR).....	123	SPI1 Master Mode (Half-Duplex, Transmit Only, CKE = 0).....	438
Illegal Opcode	123	SPI1 Master Mode (Half-Duplex, Transmit Only, CKE = 1).....	439
Security	123	SPI1 Slave Mode (Full-Duplex, CKE = 0, CKP = 0, SMP = 0)	448
Uninitialized W Register.....	123	SPI1 Slave Mode (Full-Duplex, CKE = 0, CKP = 1, SMP = 0)	446
Master Clear (MCLR) Pin Reset	123	SPI1 Slave Mode (Full-Duplex, CKE = 1, CKP = 0, SMP = 0)	442
Power-on Reset (POR)	123	SPI1 Slave Mode (Full-Duplex, CKE = 1, CKP = 1, SMP = 0)	444
RESET Instruction (SWR).....	123	SPI2 Master Mode (Full-Duplex, CKE = 0, CKP = x, SMP = 1)	429
Resources	124	SPI2 Master Mode (Full-Duplex, CKE = 1, CKP = x, SMP = 1)	428
Trap Conflict Reset (TRAPR).....	123	SPI2 Master Mode (Half-Duplex, Transmit Only, CKE = 0).....	426
Watchdog Timer Time-out Reset (WDTO).....	123	SPI2 Master Mode (Half-Duplex, Transmit Only, CKE = 1).....	427
Resources Required for Digital PFC	32, 34	SPI2 Slave Mode (Full-Duplex, CKE = 0, CKP = 0, SMP = 0)	436
Revision History	507	SPI2 Slave Mode (Full-Duplex, CKE = 0, CKP = 1, SMP = 0)	434
S		SPI2 Slave Mode (Full-Duplex, CKE = 1, CKP = 0, SMP = 0)	430
Serial Peripheral Interface (SPI)	265	SPI2 Slave Mode (Full-Duplex, CKE = 1, CKP = 1, SMP = 0)	432
Software Stack Pointer (SSP).....	111	Timer1-Timer5 External Clock	418
Special Features of the CPU	379	TimerQ (QE1 Module) External Clock	423
SPI		UARTx I/O	454
Control Registers	268	U	
Helpful Tips.....	267	Universal Asynchronous Receiver	
Resources	267	Transmitter (UART)	281
T		Control Registers.....	283
Temperature and Voltage Specifications		Helpful Tips.....	282
AC	413, 471	Resources	282
Thermal Operating Conditions	402	User ID Words	384
Thermal Packaging Characteristics	402	V	
Timer1.....	203	Voltage Regulator (On-Chip).....	384
Control Register	205	W	
Resources	204	Watchdog Timer (WDT).....	379, 385
Timer2/3 and Timer4/5.....	207	Programming Considerations	385
Control Registers	210	WWW Address	524
Resources	209	WWW, On-Line Support	23
Timing Diagrams			
10-Bit ADC Conversion (CHPS<1:0> = 01, SIMSAM = 0, ASAM = 0, SSRC<2:0> = 000, SSRCG = 0).....	464		
10-Bit ADC Conversion (CHPS<1:0> = 01, SIMSAM = 0, ASAM = 1, SSRC<2:0> = 111, SSRCG = 0, SAMC<4:0> = 00010)	464		
12-Bit ADC Conversion (ASAM = 0, SSRC<2:0> = 000, SSRCG = 0)	462		
BOR and Master Clear Reset	416		
ECANx I/O	454		
External Clock.....	414		
High-Speed PWMx Fault	422		
High-Speed PWMx Module.....	422		
I/O Characteristics	416		
I2Cx Bus Data (Master Mode)	450		
I2Cx Bus Data (Slave Mode)	452		
I2Cx Bus Start/Stop Bits (Master Mode).....	450		
I2Cx Bus Start/Stop Bits (Slave Mode).....	452		